

Material classes and atomic bonding

What holds everything together?

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$$(Elv'')'' = q - \rho A \ddot{v} \quad \Delta \int_a^b \epsilon \Theta + \Omega \int \delta e^{i\pi} \cdot \infty = \{2.718281828\} \quad \chi^2 \Sigma! \quad \sqrt{17}$$

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You're a mechanic, right? Why don't you just build something?

Kid to Tony Stark in Iron Man 3



$$(Elv'')'' = q - \rho A \ddot{v} \quad \Delta \int_a^b \epsilon \Theta + \Omega \int \delta e^{i\pi} \cdot \infty = \{2.718281828\} \quad \chi^2 \Sigma! \quad \sqrt{17}$$

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Material classes - properties

Polymers



Ceramics



Metals



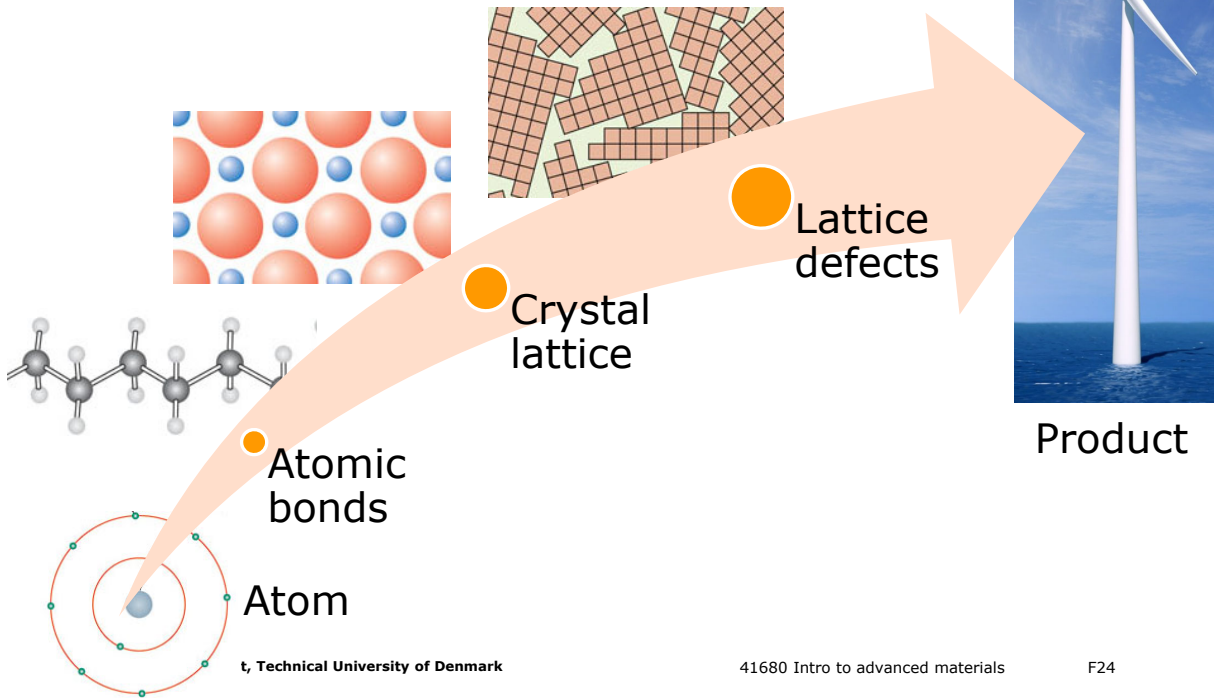
Group exercise Material classes (Pros and Cons)

Class	Metals	Ceramics	Polymers
Pros	Group 1	Group 2	Group 3
Discuss the advantages and disadvantages of using materials from the different classes in groups. Present the findings of your assigned task in plenum, e.g. group 2 should summarise advantages and disadvantages of ceramics			
Cons			



Advanced materials

Atoms - Microstructure - Properties



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Atomic bonds (in solids)

$$(Elv'')'' = q - \rho A \ddot{v} \int_a^b \epsilon \Theta + \Omega \int \delta e^{i\pi} \cdot \frac{\sqrt{17}}{\infty} = \frac{2.718281828}{\chi^2} \sum \gg \text{!}$$

H																He	
Li	Be											B	C	N	O	F	Ne
Na	Mg											Al	Si	P	S	Cl	Ar
K	Ca	Sc	Ti	V	Cr	Mn	Fe	Co	Ni	Cu	Zn	Ga	Ge	As	Se	Br	Kr
Rb	Sr	Y	Zr	Nb	Mo	Tc	Ru	Rh	Pd	Ag	Cd	In	Sn	Sb	Te	I	Xe
Cs	Ba	L	Hf	Ta	W	Re	Os	Ir	Pt	Au	Hg	Tl	Pb	Bi	Po	At	Rn
Fr	Ra	A	Rf	Db	Sg	Bh	Hs	Mt	Ds	Rg	Cn	Nh	Fl	Mc	Lv	Ts	Og
		L	La	Ce	Pr	Nd	Pm	Sm	Eu	Gd	Tb	Dy	Ho	Er	Tm	Yb	Lu
		A	Ac	Th	Pa	U	Np	Pu	Am	Cm	Bk	Cf	Es	Fm	Md	No	Lr
	Alkali metals					Actinides					Metalloids						
	Alkaline earth metals					Transition metals					Non-metals						
	Lanthanides					Other metals					Noble gases						

Electronegativity X (Pauling) F24

- Tendency to attract and bond electrons

IA																	0				
H																	He				
2.1																	-				
Li	Be															B	C	N	O	F	Ne
1.0	1.5															2.0	2.5	3.0	3.5	4.0	-
Na	Mg															Al	Si	P	S	Cl	Ar
0.9	1.2															1.5	1.8	2.1	2.5	3.0	-
		IIIB	IVB	VB	VIB	VII B	VIII			IB	IIB										
K	Ca	Sc	Ti	V	Cr	Mn	Fe	Co	Ni	Cu	Zn	Ga	Ge	As	Se	Br	Kr				
0.8	1.0	1.3	1.5	1.6	1.6	1.5	1.8	1.8	1.8	1.9	1.6	1.6	1.8	2.0	2.4	2.8	-				
Rb	Sr	Y	Zr	Nb	Mo	Tc	Ru	Rh	Pd	Ag	Cd	In	Sn	Sb	Te	I	Xe				
0.8	1.0	1.2	1.4	1.6	1.8	1.9	2.2	2.2	2.2	1.9	1.7	1.7	1.8	1.9	2.1	2.5	-				
Cs	Ba	La-Lu	Hf	Ta	W	Re	Os	Ir	Pt	Au	Hg	Tl	Pb	Bi	Po	At	Rn				
0.7	0.9	1.1-1.2	1.3	1.5	1.7	1.9	2.2	2.2	2.2	2.4	1.9	1.8	1.8	1.9	2.0	2.2	-				
Fr	Ra	Ac-No																			
0.7	0.9	1.1-1.7																			



Lower electronegativity
(donates electrons)



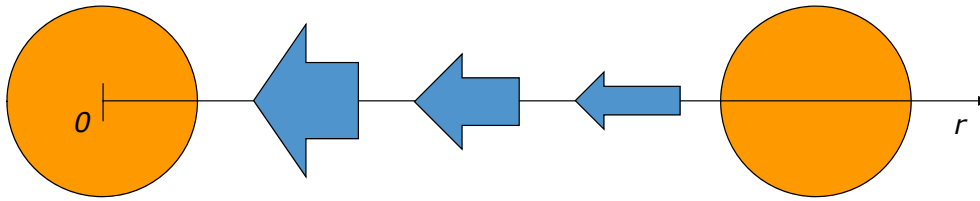
Higher electronegativity
(accepts electrons)

Interatomic forces

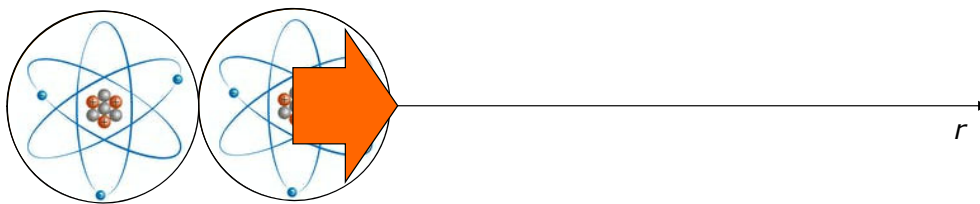
$$(Elv'')'' = q - \rho A \ddot{v} \int_a^b \epsilon \Theta + \Omega \int \delta e^{i\pi} \chi^2 \sum!$$

Interatomic forces

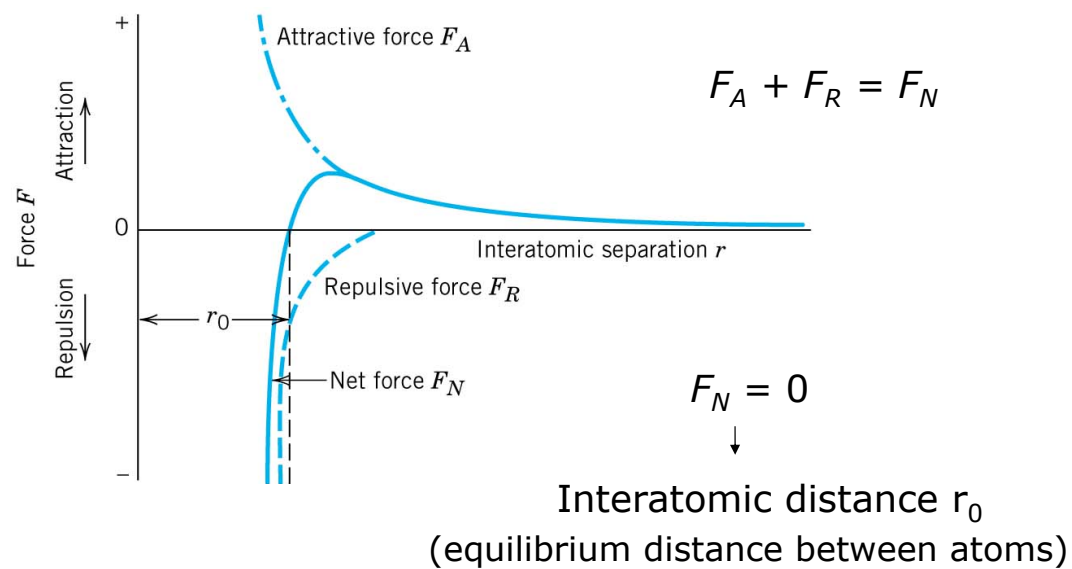
- Attraction (the stronger, the closer)



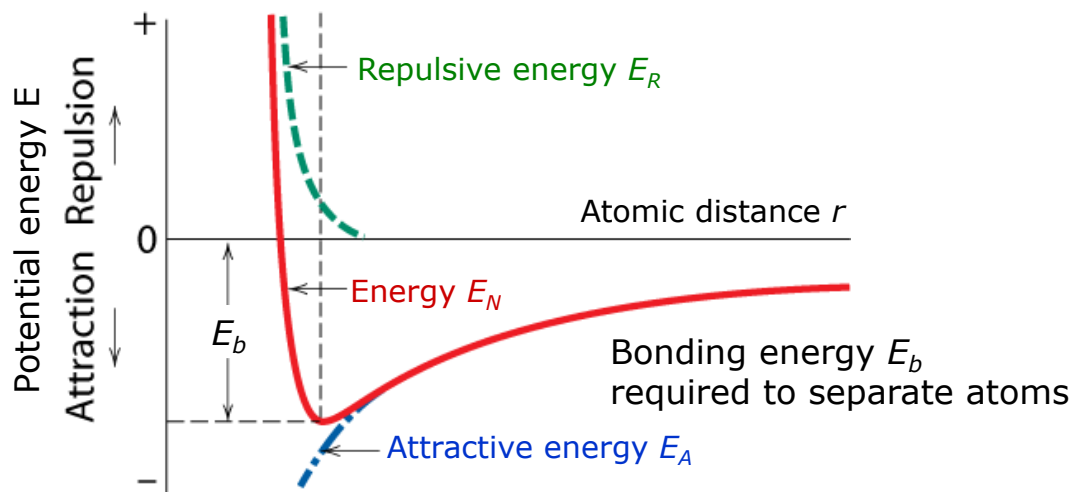
- Repulsion



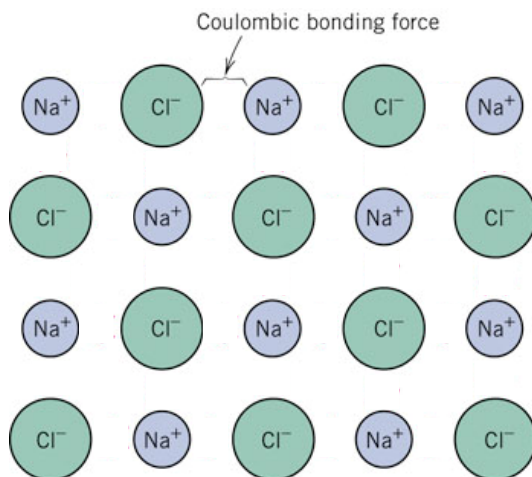
Bonding forces between atoms



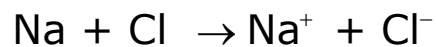
Bonding energy



Ionic bonding

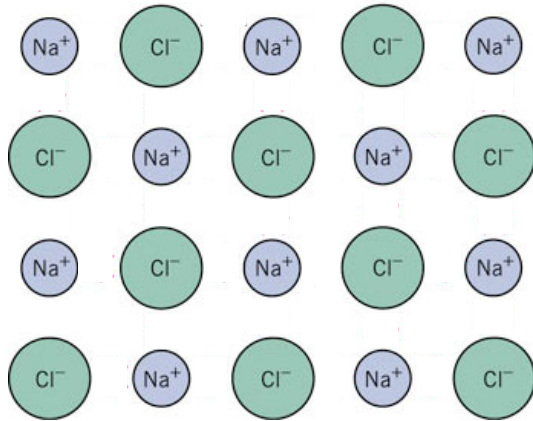


- Metal + Non-metal
- Low + high electronegativity
- Complete transfer of electron



- Atoms become ions with electrical charge
- Coulomb forces
 - Long range
- Bond
 - Without direction
 - Many neighbors

Ionic bonding



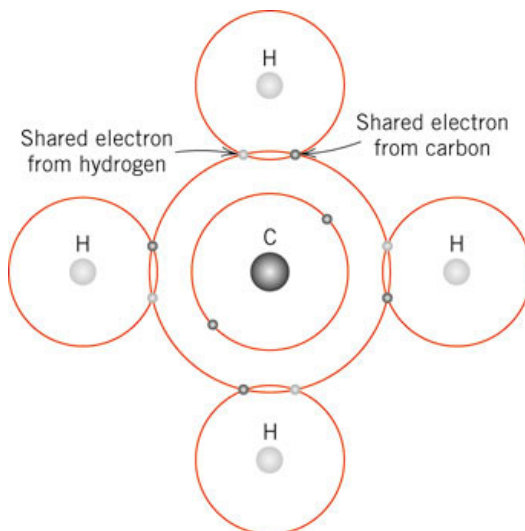
Examples

- Salt (NaCl)
- Minerals (Al_2O_3)
- Classical ceramics (SiO_2)
- Technical ceramics (MgO)

Consequences

- Low electric conductivity (DC)
- Brittle

Covalent bonding / electron pair bonding



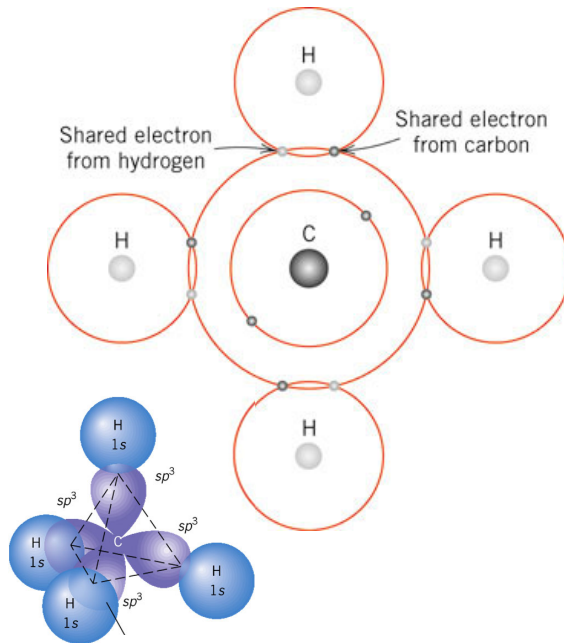
- Non-metal + Non-metal (or metalloids)
- Octet rule
- Two atoms share electron pairs

Covalent bonding

- With direction
- Only immediate neighbor
- Valence = number of possible bonds

n valence electrons	Number of bonds
$n \leq 4$	n
$n \geq 4$	$8 - n$ (n)

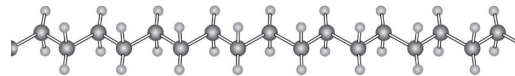
Covalent bonding / electron pair bonding



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Examples

- Molecules (H_2 , N_2 , H_2O , CH_4)
- Solid elements (Si, diamond)
- Compounds (GaAs, SiC)
- Polymers



Consequences

- Low electrical conductivity
- High thermal conductivity
- Brittle

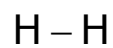
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Covalent bonding / electron pair bonding

Atoms of same kind

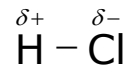
- Equally sharing of electron pair



- Nonpolar bond

Atoms with different electronegativity

- Uneven sharing of electron pair



- Polar bond
- Small electrical dipole
- Difference in electronegativity

$$\Delta X = X_A - X_B$$

Bond type: ionic vs. covalent

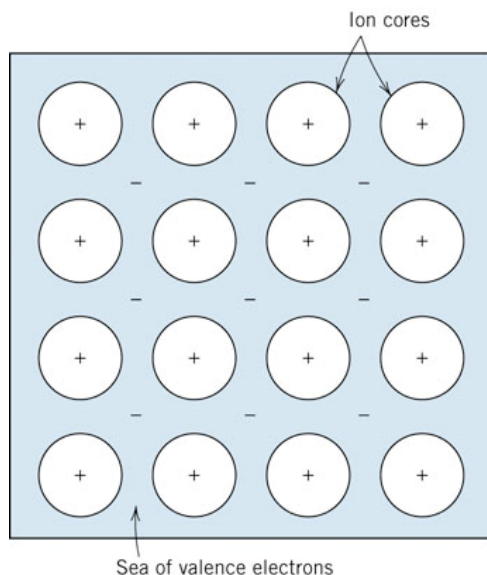
- Bonding between atoms of two elements A and B
- Never pure ionic bonds
- Fraction of ionic bond (empirical relation)

$$f_{ion} = 1 - \exp\left[-\frac{(X_A - X_B)^2}{4}\right] = 1 - e^{-\frac{(X_A - X_B)^2}{4}}$$

- Electronegativities X_A and X_B
- Fraction valid for bond A-B, not only for compound AB!
- Example: SiO_2 51%

Chemical compound	Ionic fraction
CsCl	73%
NaCl	67%
ZnS	18%

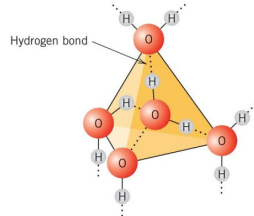
Metallic bonding



- Electrons shared between all atoms
- Valence electrons
 - Do not belong to any atom (free electrons)
 - Electron cloud
 - Conduction electrons
- Bond without direction
 - Long range
- Inner electrons localized
 - (extra covalent bond)
- Positive charge
 - Ions, not nuclei!
 - Many neighbors

Secondary bonds Hydrogen bond

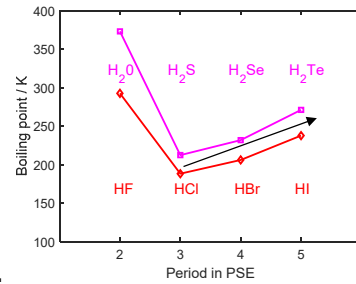
- Hydrogen ion = proton
- Hydrogen atom in covalent bond with electronegative atom



- Interaction with free electron pair (proton can switch between neighbors)

Examples

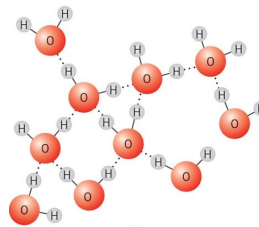
- H_2O , HF, ...
- Biomolecules (Proteins, DNA)



General: the higher the molar mass, the higher the melting temperature

Consequences

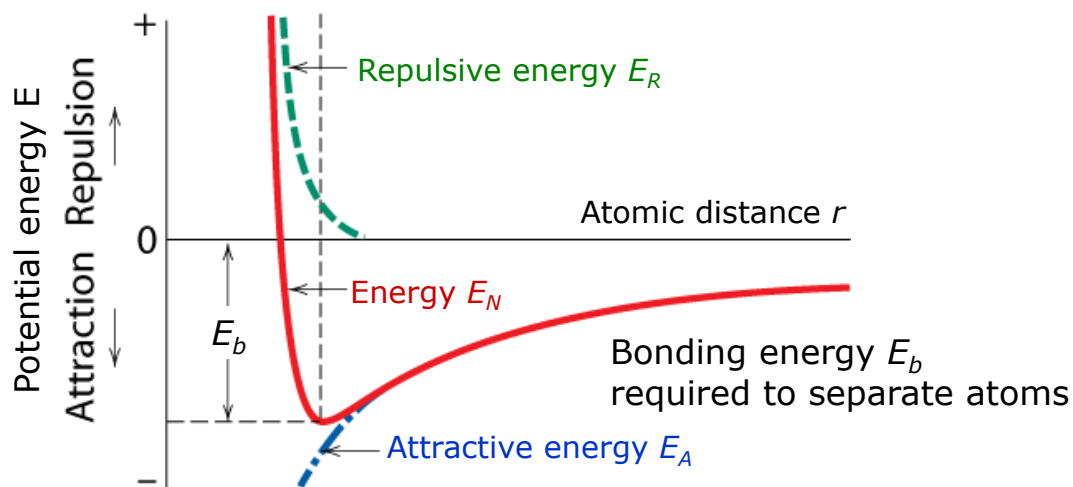
- High melting temperature
- High boiling temperature
- Low density as solid



iced materials

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Bonding energy



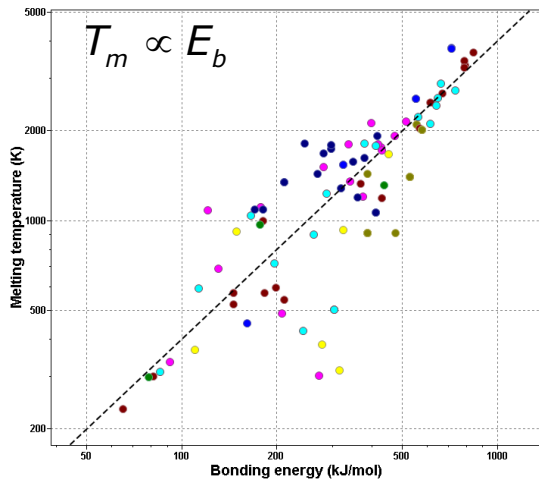
Affects materials properties

Bond energy \rightarrow melting temperature (boiling temp.)

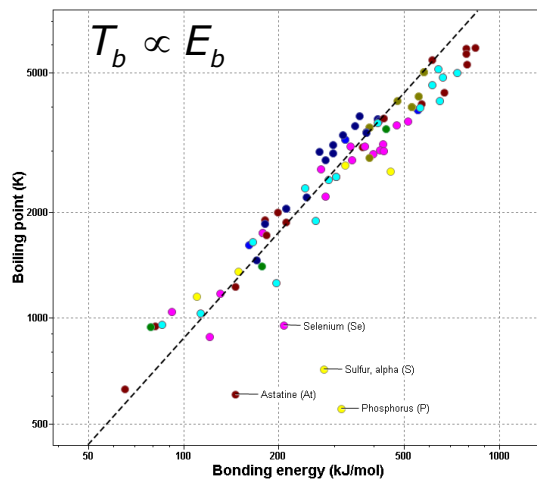
Energy profile \rightarrow Elastic modulus, thermal expansion

Property correlations

- Melting temperature T_m and bonding energy E_b
- Boiling temperature T_b and bonding energy E_b



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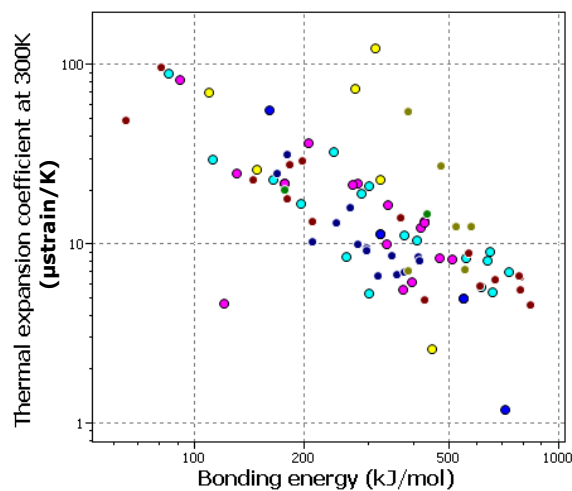


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Property correlations

- Thermal expansion coefficient and bonding energy E_b

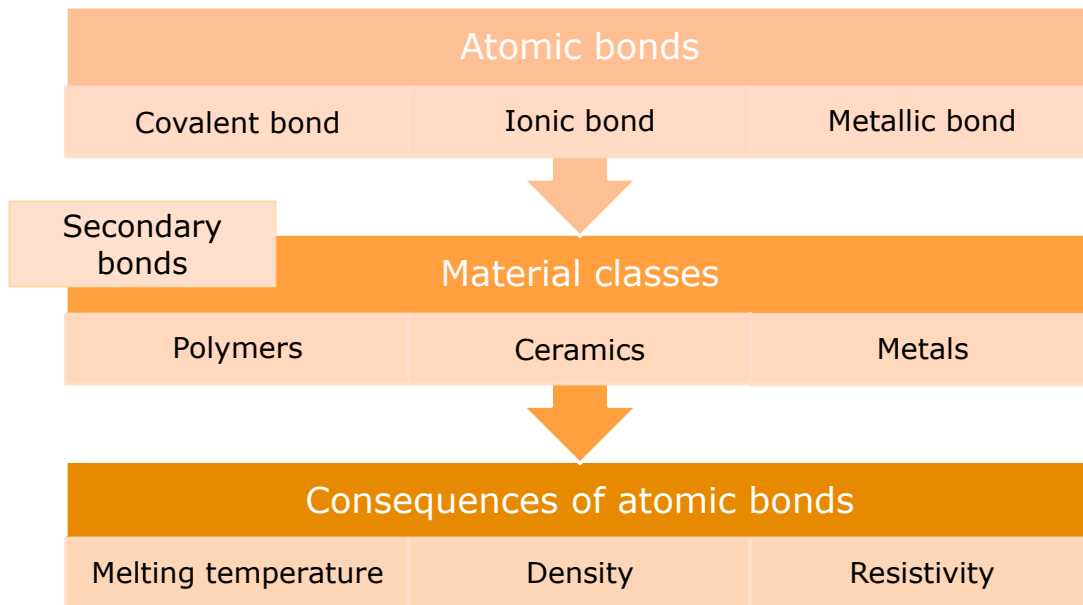


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Summary



Bond types and material classes

